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DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: Method and Apparatus for Testing Semiconductor Circuitry For Operability and Method Of Forming Apparatus For Testing Semiconductor Circuitry For Operability, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

I do not know and do not believe that the invention was ever known or used in the United States of America before our invention thereof.

I do not know and do not believe that the invention was ever patented or described in any printed publication in any country before our invention thereof or more than one year prior to this application.

I do not know and do not believe that the invention was in public use or on sale in the United States of America more than one year prior to this application.

1 PRIOR FOREIGN APPLICATIONS:

2 I hereby state that no applications for foreign patents or inventor's
3 certificates have been filed prior to the date of execution of this
4 declaration.

5 POWER OF ATTORNEY:

6 As a named Inventor, I hereby appoint the following attorneys and
7 agent to prosecute this application and transact all business in the
8 Patent and Trademark Office connected therewith: Richard J. St. John,
9 Reg. No. 19,363; David P. Roberts, Reg. No. 23,032; Randy A.
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18 I hereby declare that all statements made herein of my own
19 knowledge are true and that all statements made on information and
20 belief are believed to be true; and further that these statements were
21 made with the knowledge that willful false statements and the like so
22 made are punishable by fine or imprisonment, or both, under
23 Section 1001 of Title 18 of the United States Code and that such willful
24

1 false statement may jeopardize the validity of the application or any
2 patent issued therefrom.

3
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